

SCAN18245T Non-Inverting Transceiver with Tri-State Outputs

Check for Samples: [SCAN18245T](#)

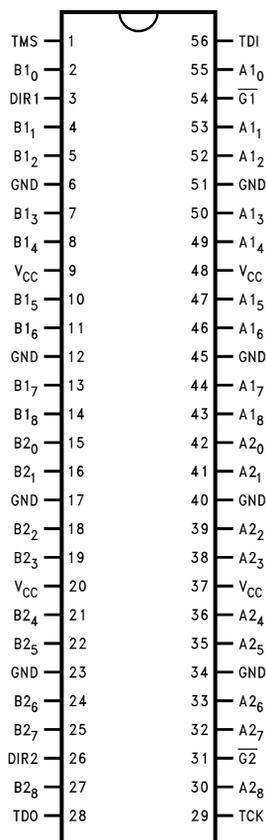
FEATURES

- IEEE 1149.1 (JTAG) Compliant
- Dual Output Enable Control Signals
- Tri-State Outputs for Bus-Oriented Applications
- 9-bit Data Busses for Parity Applications
- Reduced-Swing Outputs Source 24 mA/sink 48 mA
- Ensured to Drive 50Ω Transmission Line to TTL Input Levels of 0.8V and 2.0V
- TTL Compatible Inputs
- 25 mil Pitch Cerpack Package
- Includes CLAMP and HIGHZ Instructions
- Available as Known Good Die
- Standard Microcircuit Drawing (SMD) 5962-9311501

DESCRIPTION

The SCAN18245T is a high speed, low-power bidirectional line driver featuring separate data inputs organized into dual 9-bit bytes with byte-oriented output enable and direction control signals. This device is compliant with IEEE 1149.1 Standard Test Access Port and Boundary Scan Architecture with the incorporation of the defined boundary-scan test logic and test access port consisting of Test Data Input (TDI), Test Data Out (TDO), Test Mode Select (TMS), and Test Clock (TCK).

Connection Diagram



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

Pin Names	Description
A1 _(0–8)	Side A1 Inputs or TRI-STATE Outputs
B1 _(0–8)	Side B1 Inputs or TRI-STATE Outputs
A2 _(0–8)	Side A2 Inputs or TRI-STATE Outputs
B2 _(0–8)	Side B2 Inputs or TRI-STATE Outputs
$\overline{G1}$, $\overline{G2}$	Output Enable Pins
DIR1, DIR2	Direction of Data Flow Pins

TRUTH TABLES

Inputs ⁽¹⁾		A1 (0–8)		B1 (0–8)	
$\overline{G1}$	DIR1				
L	L	H	←	H	
L	L	L	←	L	
L	H	H	→	H	
L	H	L	→	L	
H	X	Z		Z	

- (1) H= HIGH Voltage Level
 L= LOW Voltage Level
 X= Immaterial
 Z= High Impedance

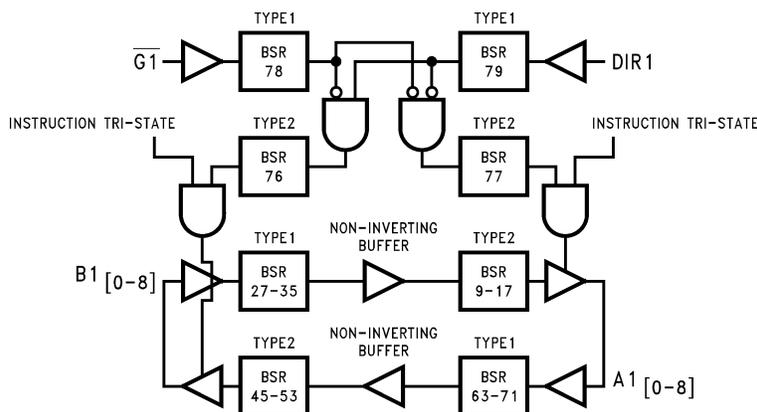
Inputs ⁽¹⁾		A2 (0–8)		B2 (0–8)	
$\overline{G2}$	DIR2				
L	L	H	←	H	
L	L	L	←	L	
L	H	H	→	H	
L	H	L	→	L	
H	X	Z		Z	

- (1) H= HIGH Voltage Level
 L= LOW Voltage Level
 X= Immaterial
 Z= High Impedance

FUNCTIONAL DESCRIPTION

The SCAN18245 consists of two sets of nine non-inverting bidirectional buffers with TRI-STATE outputs and is intended for bus-oriented applications. Direction pins (DIR1 and DIR2) LOW enables data from B ports to A ports, when HIGH enables data from A ports to B ports. The Output Enable pins ($\overline{G1}$ and $\overline{G2}$) when HIGH disables both A and B ports by placing them in a high impedance condition.

Block Diagrams



Note: BSR stands for Boundary Scan Register.

Figure 1. A1, B1, $\overline{G1}$ and DIR1

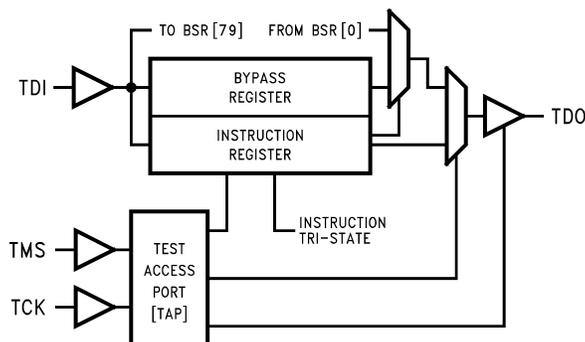
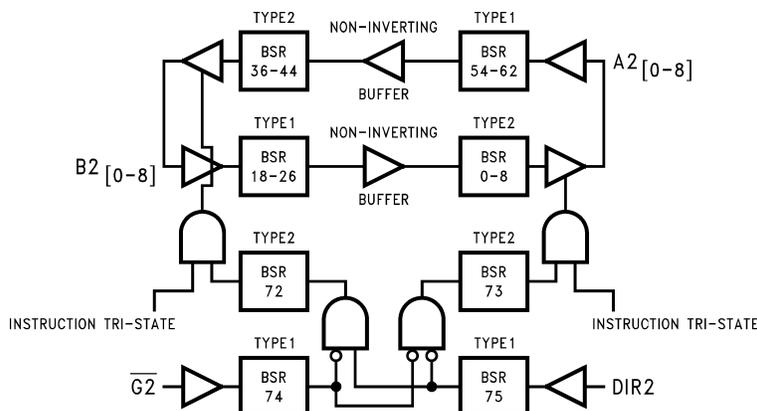


Figure 2. Tap Controller



Note: BSR stands for Boundary Scan Register.

Figure 3. A2, B2, $\overline{G2}$ and DIR2

Description of Boundary-Scan Circuitry

The scan cells used in the BOUNDARY-SCAN register are one of the following two types depending upon their location. Scan cell TYPE1 is intended to solely observe system data, while TYPE2 has the additional ability to control system data. (See IEEE Standard 1149.1 *Figure 10–11* for a further description of scan cell TYPE1 and *Figure 10–12* for a further description of scan cell TYPE2.)

Scan cell TYPE1 is located on each system input pin while scan cell TYPE2 is located at each system output pin as well as at each of the two internal active-high output enable signals. AOE controls the activity of the A-outputs while BOE controls the activity of the B-outputs. Each will activate their respective outputs by loading a logic high.

The BYPASS register is a single bit shift register stage identical to scan cell TYPE1. It captures a fixed logic low.

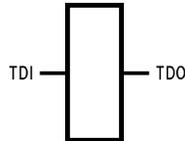


Figure 4. Bypass Register Scan Chain Definition Logic 0

The INSTRUCTION register is an eight-bit register which captures the value 00111101.

The two least significant bits of this captured value (01) are required by IEEE Std 1149.1. The upper six bits are unique to the SCAN18245T device. SCAN CMOS Test Access Logic devices do not include the IEEE 1149.1 optional identification register. Therefore, this unique captured value can be used as a “pseudo ID” code to confirm that the correct device is placed in the appropriate location in the boundary scan chain.

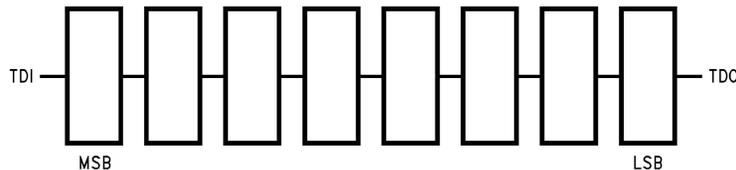


Figure 5. Instruction Register Scan Chain Definition

MSB → LSB

Instruction Code	Instruction
00000000	EXTEST
10000001	SAMPLE/PRELOAD
10000010	CLAMP
00000011	HIGHZ
All Others	BYPASS

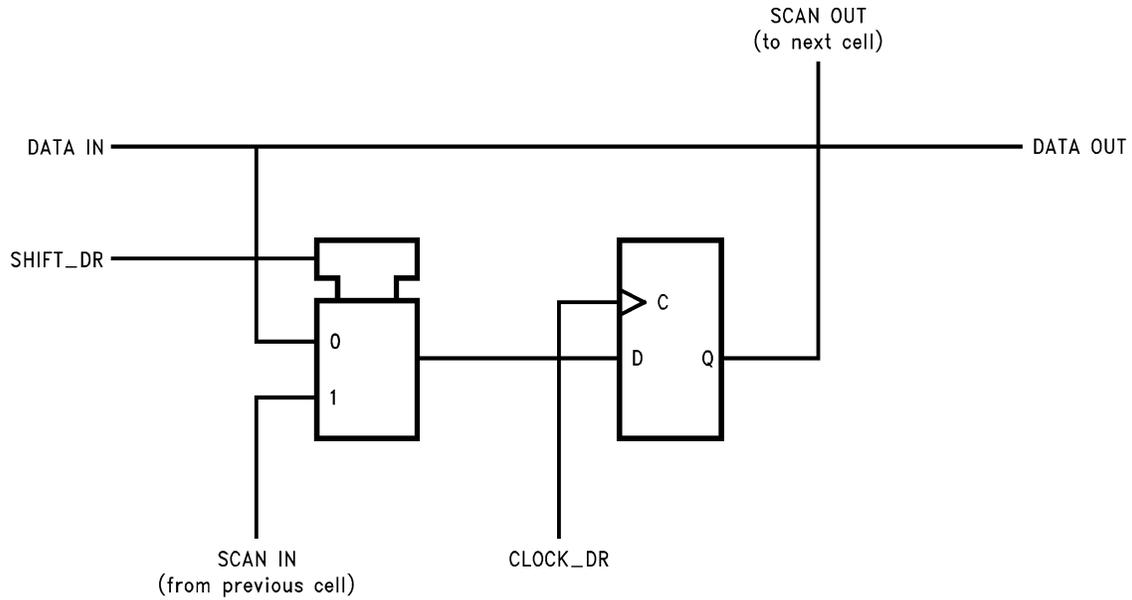


Figure 6. Scan Cell TYPE1

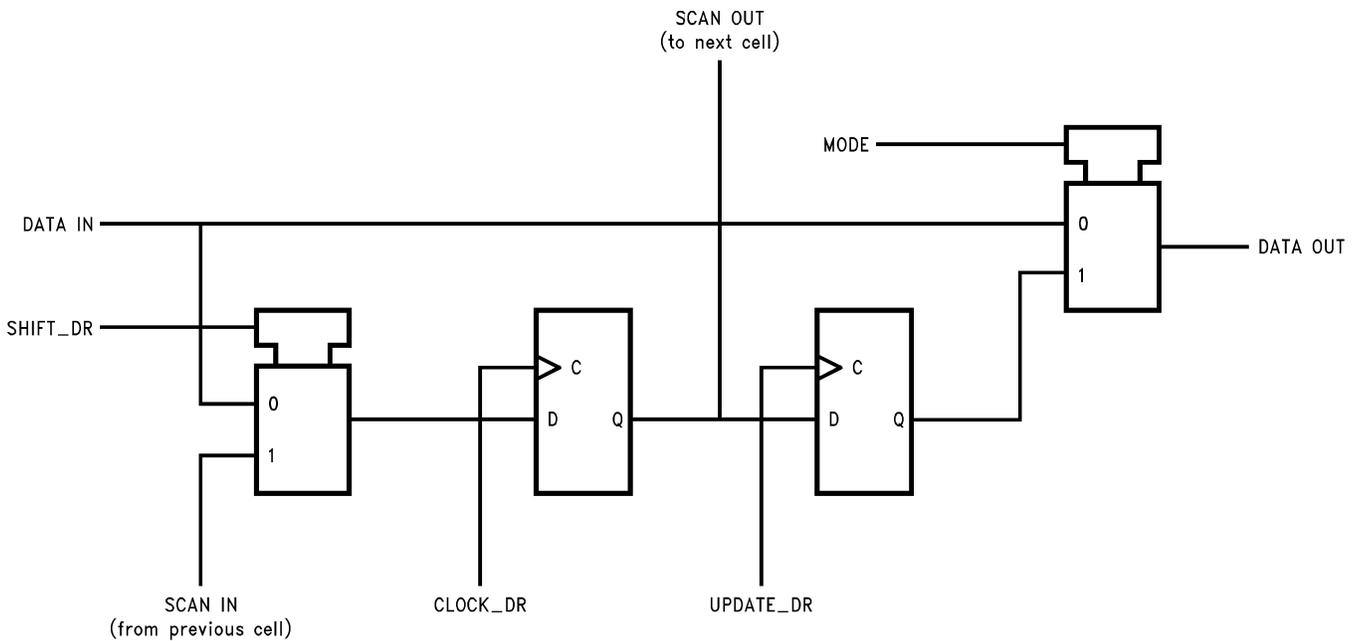


Figure 7. Scan Cell TYPE2

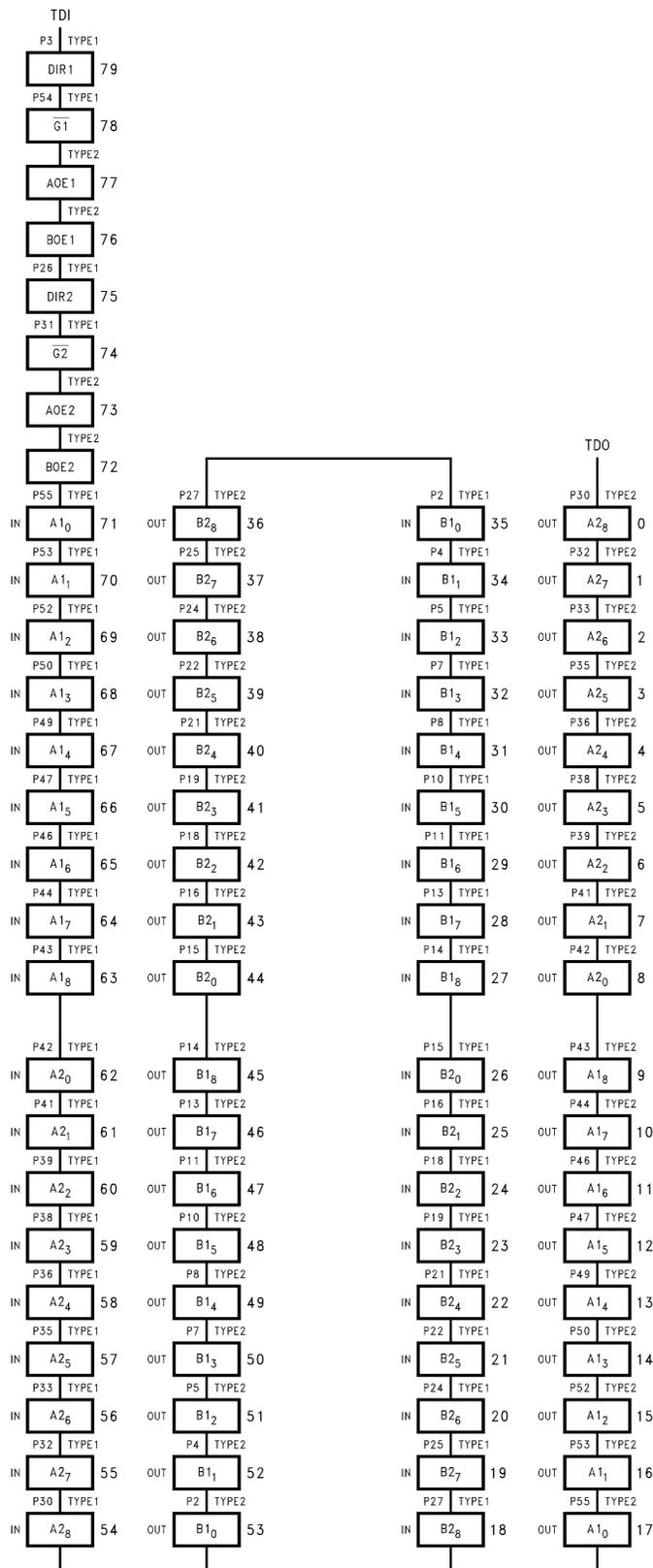


Figure 8. Boundary-Scan Register Scan Chain Definition (80 Bits in Length)

Boundary-Scan Register Definition Index

Bit No.	Pin Name	Pin No.	Pin Type	Scan Cell Type	
79	DIR1	3	Input	TYPE1	Control Signals
78	$\overline{G1}$	54	Input	TYPE1	
77	AOE ₁		Internal	TYPE2	
76	BOE ₁		Internal	TYPE2	
75	DIR2	26	Input	TYPE1	
74	$\overline{G2}$	31	Input	TYPE1	
73	AOE ₂		Internal	TYPE2	
72	BOE ₂		Internal	TYPE2	
71	A1 ₀	55	Input	TYPE1	A1-in
70	A1 ₁	53	Input	TYPE1	
69	A1 ₂	52	Input	TYPE1	
68	A1 ₃	50	Input	TYPE1	
67	A1 ₄	49	Input	TYPE1	
66	A1 ₅	47	Input	TYPE1	
65	A1 ₆	46	Input	TYPE1	
64	A1 ₇	44	Input	TYPE1	
63	A1 ₈	43	Input	TYPE1	A2-in
62	A2 ₀	42	Input	TYPE1	
61	A2 ₁	41	Input	TYPE1	
60	A2 ₂	39	Input	TYPE1	
59	A2 ₃	38	Input	TYPE1	
58	A2 ₄	36	Input	TYPE1	
57	A2 ₅	35	Input	TYPE1	
56	A2 ₆	33	Input	TYPE1	
55	A2 ₇	32	Input	TYPE1	B1-out
54	A2 ₈	30	Input	TYPE1	
53	B1 ₀	2	Output	TYPE2	
52	B1 ₁	4	Output	TYPE2	
51	B1 ₂	5	Output	TYPE2	
50	B1 ₃	7	Output	TYPE2	
49	B1 ₄	8	Output	TYPE2	
48	B1 ₅	10	Output	TYPE2	
47	B1 ₆	11	Output	TYPE2	B2-out
46	B1 ₇	13	Output	TYPE2	
45	B1 ₈	14	Output	TYPE2	
44	B2 ₀	15	Output	TYPE2	
43	B2 ₁	16	Output	TYPE2	
42	B2 ₂	18	Output	TYPE2	
41	B2 ₃	19	Output	TYPE2	
40	B2 ₄	21	Output	TYPE2	
39	B2 ₅	22	Output	TYPE2	
38	B2 ₆	24	Output	TYPE2	
37	B2 ₇	25	Output	TYPE2	
36	B2 ₈	27	Output	TYPE2	

Boundary-Scan Register Definition Index (continued)

Bit No.	Pin Name	Pin No.	Pin Type	Scan Cell Type
35	B1 ₀	2	Input	TYPE1
34	B1 ₁	4	Input	TYPE1
33	B1 ₂	5	Input	TYPE1
32	B1 ₃	7	Input	TYPE1
31	B1 ₄	8	Input	TYPE1
30	B1 ₅	10	Input	TYPE1
29	B1 ₆	11	Input	TYPE1
28	B1 ₇	13	Input	TYPE1
27	B1 ₈	14	Input	TYPE1
26	B2 ₀	15	Input	TYPE1
25	B2 ₁	16	Input	TYPE1
24	B2 ₂	18	Input	TYPE1
23	B2 ₃	19	Input	TYPE1
22	B2 ₄	21	Input	TYPE1
21	B2 ₅	22	Input	TYPE1
20	B2 ₆	24	Input	TYPE1
19	B2 ₇	25	Input	TYPE1
18	B2 ₈	27	Input	TYPE1
17	A1 ₀	55	Output	TYPE2
16	A1 ₁	53	Output	TYPE2
15	A1 ₂	52	Output	TYPE2
14	A1 ₃	50	Output	TYPE2
13	A1 ₄	49	Output	TYPE2
12	A1 ₅	47	Output	TYPE2
11	A1 ₆	46	Output	TYPE2
10	A1 ₇	44	Output	TYPE2
9	A1 ₈	43	Output	TYPE2
8	A2 ₀	42	Output	TYPE2
7	A2 ₁	41	Output	TYPE2
6	A2 ₂	39	Output	TYPE2
5	A2 ₃	38	Output	TYPE2
4	A2 ₄	36	Output	TYPE2
3	A2 ₅	35	Output	TYPE2
2	A2 ₆	33	Output	TYPE2
1	A2 ₇	32	Output	TYPE2
0	A2 ₈	30	Output	TYPE2



These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

ABSOLUTE MAXIMUM RATINGS ⁽¹⁾⁽²⁾

Supply Voltage (V_{CC})		-0.5V to +7.0V
DC Input Diode Current (I_{IK})	$V_I = -0.5V$	-20 mA
	$V_I = V_{CC} + 0.5V$	+20 mA
DC Output Diode Current (I_{OK})	$V_O = -0.5V$	-20 mA
	$V_O = V_{CC} + 0.5V$	+20 mA
DC Output Voltage (V_O)		-0.5V to $V_{CC} + 0.5V$
DC Output Source/Sink Current (I_O)		± 70 mA
DC V_{CC} or Ground Current	Per Output Pin	± 70 mA
Junction Temperature	Cerpack	+175°C
Storage Temperature		-65°C to +150°C
ESD (Min)		2000V

- (1) Absolute maximum ratings are those values beyond which damage to the device may occur. The databook specifications should be met, without exception, to ensure that the system design is reliable over its power supply, temperature, and output/input loading variables. Texas Instruments does not recommend operation of SCAN circuits outside databook specifications.
- (2) If Military/Aerospace specified devices are required, please contact the Texas Instruments Sales Office/ Distributors for availability and specifications.

RECOMMENDED OPERATING CONDITIONS

Supply Voltage (V_{CC})	SCAN Products	4.5V to 5.5V
Input Voltage (V_I)		0V to V_{CC}
Output Voltage (V_O)		0V to V_{CC}
Operating Temperature (T_A)	Military	-55°C to +125°C
Minimum Input Edge Rate dV/dt	V_{IN} from 0.8V to 2.0V V_{CC} @ 4.5V, 5.5V	125 mV/ns

DC ELECTRICAL CHARACTERISTICS

All outputs loaded; thresholds associated with output under test.

Symbol	Parameter	V_{CC} (V)	Military	Units	Conditions	
			$T_A = -55^\circ\text{C to } +125^\circ\text{C}$			
			Specified Limits			
V_{IH}	Minimum High Input Voltage	4.5	2.0	V	$V_{OUT} = 0.1V$ or $V_{CC} - 0.1V$	
		5.5	2.0			
V_{IL}	Maximum Low Input Voltage	4.5	0.8	V	$V_{OUT} = 0.1V$ or $V_{CC} - 0.1V$	
		5.5	0.8			
V_{OH}	Minimum High Output Voltage	4.5	3.15	V	$I_{OUT} = -50 \mu A$	
		5.5	4.15			
			4.5	2.4	V	$V_{IN} = V_{IL}$ or V_{IH} $I_{OH} = -24 \text{ mA}$
			5.5	2.4		
V_{OL}	Maximum Low Output Voltage	4.5	0.1	V	$I_{OUT} = 50 \mu A$	
		5.5	0.1			
			4.5	0.55	V	$V_{IN} = V_{IL}$ or V_{IH} $I_{OL} = 48 \text{ mA}$
			5.5	0.55		
I_{IN}	Maximum Input Leakage Current	5.5	± 1.0	μA	$V_I = V_{CC}, \text{ GND}$	
I_{IN} TDI, TMS	Maximum Input Leakage	5.5	3.7	μA	$V_I = V_{CC}$	
			-385	μA	$V_I = \text{GND}$	
	Minimum Input Leakage	5.5	-160	μA	$V_I = \text{GND}$	
I_{OLD}	Minimum Dynamic Output Current ⁽¹⁾	5.5	63	mA	$V_{OLD} = 0.8V \text{ Max}$	
I_{OHD}			-27	mA	$V_{OHD} = 2.0V \text{ Min}$	

- (1) Maximum test duration 2.0 ms, one output loaded at a time.

DC ELECTRICAL CHARACTERISTICS (continued)

All outputs loaded; thresholds associated with output under test.

Symbol	Parameter	V _{CC} (V)	Military		Units	Conditions
			T _A = -55°C to +125°C			
			Specified Limits			
I _{OZT}	Maximum I/O Leakage Current	5.5	±11.0		μA	V _I (OE) = V _{IL} , V _{IH}
						V _I = V _{CC} , GND
						V _O = V _{CC} , GND
I _{OS}	Output Short Circuit Current	5.5	-100		mA (min)	V _O = 0V
I _{CC}	Maximum Quiescent Supply Current	5.5	168		μA	V _O = High TDI, TMS = V _{CC}
		5.5	930		μA	V _O = High TDI, TMS = GND
I _{CCt}	Maximum I _{CC} Per Input	5.5	2.0		mA	V _I = V _{CC} -2.1V
		5.5	2.15		mA	TDI/TMS Pin, test one with the other floating

NOISE SPECIFICATIONS

Symbol	Parameter	V _{CC} (V)	Military		Units	Fig. No.
			T _A = -55°C to +125°C			
			Specified Limits			
V _{OLP}	Maximum High Output Noise ⁽¹⁾⁽²⁾	5.0	0.8		V	
V _{OLV}	Minimum Low Output Noise ⁽¹⁾⁽²⁾	5.0	-0.8		V	

- (1) Maximum number of outputs that can switch simultaneously is n. (n-1) outputs are switched LOW and one output held LOW.
(2) Maximum number of outputs that can switch simultaneously is n. (n-1) outputs are switched HIGH and one output held HIGH.

AC ELECTRICAL CHARACTERISTICS

Normal Operation

Symbol	Parameter	V _{CC} (V) ⁽¹⁾	Military		Units	Fig. No.
			T _A = -55°C to +125°C C _L = 50 pF			
			Min	Max		
t _{PLH} , t _{PHL}	Propagation Delay A to B, B to A	5.0	1.6 1.6	10.0 11.0	ns	
t _{PLZ} , t _{PHZ}	Disable Time	5.0	1.2 1.2	10.0 9.5	ns	
t _{PZL} , t _{PZH}	Enable Time	5.0	1.6 1.6	13.0 11.0	ns	

- (1) Voltage Range 5.0 is 5.0V ±0.5V. All Input Timing Delays involving TCK are measured from the rising edge of TCK.

AC ELECTRICAL CHARACTERISTICS

Scan Test Operation

All Propagation Delays involving TCK are measured from the falling edge of TCK.

Symbol	Parameter	V _{CC} (V) ⁽¹⁾	Military		Units	Fig. No.
			T _A = -55°C to +125°C C _L = 50 pF			
			Min	Max		
t _{PLH} , t _{PHL}	Propagation Delay TCK to TDO	5.0	2.8 2.8	15.8 15.8	ns	
t _{PLZ} , t _{PHZ}	Disable Time TCK to TDO	5.0	2.0 2.0	12.8 12.8	ns	
t _{PZL} , t _{PZH}	Enable Time TCK to TDO	5.0	2.4 2.4	16.7 16.7	ns	
t _{PLH} , t _{PHL}	Propagation Delay TCK to Data Out During Update-DR State	5.0	4.0 4.0	21.7 21.7	ns	
t _{PLH} , t _{PHL}	Propagation Delay TCK to Data Out During Update-IR State	5.0	4.0 4.0	21.2 21.2	ns	
t _{PLH} , t _{PHL}	Propagation Delay TCK to Data Out During Test Logic Reset State	5.0	4.4 4.4	23.0 23.0	ns	
t _{PLZ} , t _{PHZ}	Propagation Delay TCK to Data Out During Update-DR State	5.0	3.2 3.2	19.6 19.6	ns	
t _{PLZ} , t _{PHZ}	Propagation Delay TCK to Data Out During Update-IR State	5.0	2.8 2.8	20.9 20.9	ns	
t _{PLZ} , t _{PHZ}	Propagation Delay TCK to Data Out During Test Logic Reset State	5.0	2.8 2.8	21.8 21.8	ns	
t _{PZL} , t _{PZH}	Propagation Delay TCK to Data Out During Update-DR State	5.0	4.0 4.0	22.6 22.6	ns	
t _{PZL} , t _{PZH}	Propagation Delay TCK to Data Out During Update-IR State	5.0	3.2 3.2	23.7 23.7	ns	
t _{PZL} , t _{PZH}	Propagation Delay TCK to Data Out During Test Logic Reset State	5.0	3.6 3.6	24.9 24.9	ns	

(1) Voltage Range 5.0 is 5.0V ±0.5V. All Input Timing Delays involving TCK are measured from the rising edge of TCK.

AC OPERATING REQUIREMENTS

Scan Test Operation

Symbol	Parameter	V_{CC} (V) ⁽¹⁾	Military	Units	Fig. No.
			$T_A = -55^\circ\text{C to } +125^\circ\text{C}$ $C_L = 50 \text{ pF}$		
			Specified Minimum		
t_S	Setup Time, H or L Data to TCK ⁽²⁾	5.0	0.0	ns	
t_H	Hold Time, H or L TCK to Data ⁽²⁾	5.0	6.5	ns	
t_S	Setup Time, H or L $\overline{G1}$, $\overline{G2}$ to TCK ⁽³⁾	5.0	0.0	ns	
t_H	Hold Time, H or L TCK to $\overline{G1}$, $\overline{G2}$ ⁽³⁾	5.0	4.0	ns	
t_S	Setup Time, H or L DIR1, DIR2 to TCK ⁽⁴⁾	5.0	0.0	ns	
t_H	Hold Time, H or L TCK to DIR1, DIR2 ⁽⁴⁾	5.0	4.0	ns	
t_S	Setup Time, H or L Internal AOE _n , BOE _n to TCK ⁽⁵⁾	5.0	1.0	ns	
t_H	Hold Time, H or L TCK to Internal AOE _n , BOE ⁽⁵⁾	5.0	4.0	ns	
t_S	Setup Time, H or L TMS to TCK	5.0	7.0	ns	
t_H	Hold Time, H or L TCK to TMS	5.0	2.0	ns	
t_S	Setup Time, H or L TDI to TCK	5.0	1.0	ns	
t_H	Hold Time, H or L TCK to TDI	5.0	3.5	ns	
t_W	Pulse Width	H	12.0	ns	
		L	5.0		
f_{max}	Maximum TCK Clock Frequency	5.0	25	MHz	
T_{PU}	Wait Time, Power Up to TCK	5.0	100	ns	
T_{DN}	Power Down Delay	0.0	100	ms	

(1) Voltage Range 5.0 is 5.0V \pm 0.5V. All Input Timing Delays involving TCK are measured from the rising edge of TCK.

(2) Timing pertains to the TYPE1 BSR and TYPE2 BSR after the buffer (BSR 0–8, 9–17, 18–26, 27–35, 36–44, 45–53, 54–62, 63–71).

(3) Timing pertains to BSR 74 and 78 only.

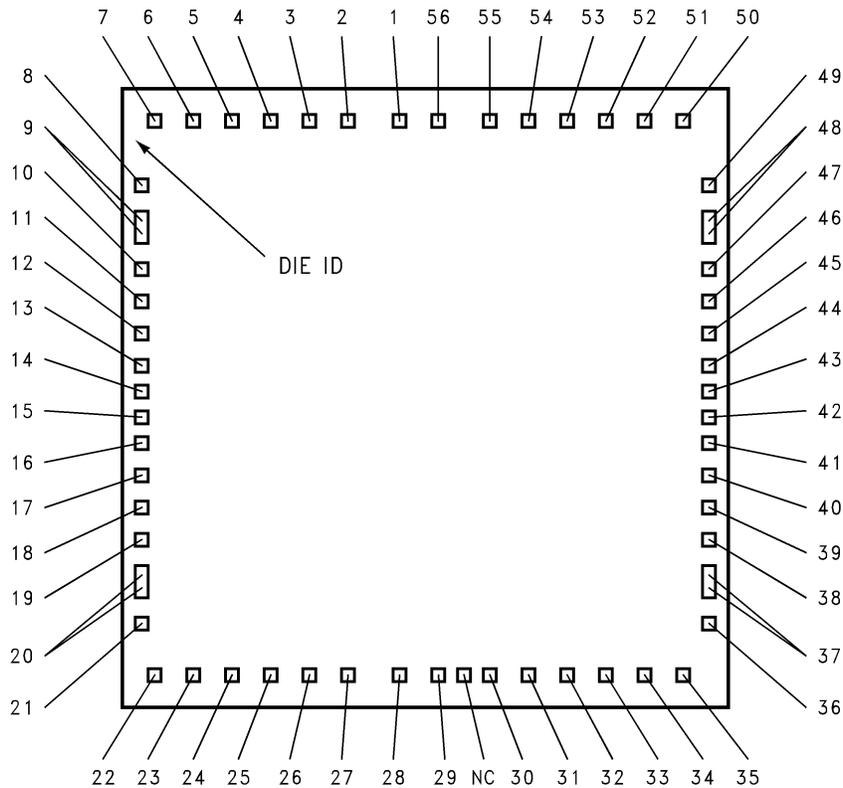
(4) Timing pertains to BSR 75 and 79 only.

(5) Timing pertains to BSR 72, 73, 76 and 77 only.

CAPACITANCE

Symbol	Parameter	Typ	Units	Conditions
C_{IN}	Input Pin Capacitance	4	pF	$V_{CC} = 5.0\text{V}$
$C_{I/O}$	Input/Output Capacitance	20	pF	$V_{CC} = 5.0\text{V}$
C_{PD}	Power Dissipation Capacitance	41	pF	$V_{CC} = 5.0\text{V}$

PAD DIAGRAM



PAD LOCATIONS

Signal Number	Signal Name	Pad Location ⁽¹⁾
1	TMS	-8.58, 77.81
2	B1 ₀	-19.94, 77.81
3	DIR1	-30.50, 77.81
4	B1 ₁	-40.98, 77.81
5	B1 ₂	-53.59, 77.81
6	GND	-63.73, 77.81
7	B1 ₃	-74.47, 77.81
8	B1 ₄	-79.73, 62.30
9	V _{CC}	-79.73, 51.55
		-79.73, 46.28
10	B1 ₅	-79.73, 36.05
11	B1 ₆	-79.73, 27.48
12	GND	-79.72, 19.46
13	B1 ₇	-79.73, 10.09
14	B1 ₈	-79.73, 3.46
15	B2 ₀	-79.73, -3.43
16	B2 ₁	-79.73, -10.06
17	GND	-79.72, -19.43
18	B2 ₂	-79.73, -27.45
19	B2 ₃	-79.73, -36.02

(1) X, Y coordinates measured in mils from center of die.

PAD LOCATIONS (continued)

Signal Number	Signal Name	Pad Location ⁽¹⁾
20	V _{CC}	-79.73, -46.24
		-79.73, -51.52
21	B ₂₄	-79.73, -62.27
22	B ₂₅	-74.47, -77.81
23	GND	-63.73, -77.81
24	B ₂₆	-53.59, -77.81
25	B ₂₇	-40.98, -77.81
26	DIR2	-30.50, -77.81
27	B ₂₈	-19.94, -77.81
28	TDO	-8.58, -77.81
29	TCK	5.54, -77.81
30	A ₂₈	19.94, -77.81
31	$\overline{G2}$	30.50, -77.81
32	A ₂₇	40.98, -77.81
33	A ₂₆	53.59, -77.81
34	GND	63.73, -77.81
35	A ₂₅	74.47, -77.81
36	A ₂₄	79.73, -62.27
37	V _{CC}	79.73, -51.50
		79.73, -46.23
38	A ₂₃	79.73, -36.02
39	A ₂₂	79.73, -27.40
40	GND	79.73, -19.43
41	A ₂₁	79.73, -10.06
42	A ₂₀	79.73, -3.43
43	A ₁₈	79.73, 3.46
44	A ₁₇	79.73, 10.09
45	GND	79.72, 19.46
46	A ₁₆	79.73, 27.43
47	A ₁₅	79.73, 36.05
48	V _{CC}	79.73, 46.26
		79.73, 51.54
49	A ₁₄	79.73, 62.30
50	A ₁₃	74.47, 77.81
51	GND	63.73, 77.81
52	A ₁₂	53.59, 77.81
53	A ₁₁	40.98, 77.81
54	$\overline{G1}$	30.50, 77.81
55	A ₁₀	19.94, 77.81
56	TDI	5.54, 77.81

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